



AMENDMENT UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 2827
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q66510

Toshio SHINTANI, et al.

Appln. No.: 09/974,048

Group Art Unit: 2827

Confirmation No.: 7616

Examiner: Tuan T. DINH

Filed: October 11, 2001

For: CIRCUIT BOARD AND CONNECTION STRUCTURE OF TERMINAL PORTION OF
THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.116

ATTN: BOX AF
Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated December 20, 2002, please amend the above-
identified application as follows:

IN THE CLAIMS:

1. (Currently Amended) A circuit board comprising:
 - a terminal portion connected with an external terminal formed in an external circuit, said terminal portion provided with a nickel plating layer and a soldering bump;
 - wherein a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm ,

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